

**AMENDMENTS TO THE SPECIFICATION:**

Please amend page 14, paragraph [0031] of the Specification as follows:

Preferably, the fixed engagement member 30 and the movable engagement member 31 are respectively provided with inclined surfaces 30a and 31a for supporting the front and rear peripheral edges of the wafer W, such that the wafer W is not disengaged from the engagement members 30 and 31 due to the wafer's own weight. Each of the substrate support device 20 preferably has seats 34 and 35 having inclined surfaces 34a and 35a, respectively, and serving as spacers for receiving the front and rear peripheral portions of the wafer W, such that a gap (g) is formed between the lower surface of the substrate support device 20 and the upper surface of the wafer W supported by the same. In this embodiment, a pair of right and left seats 34 are disposed on the right and left distal ends of the substrate support device 20, respectively, while a pair of right and left seats 35 are disposed on the right and left proximal ends of the substrate support device 20, respectively. The seat 34 and the fixed engagement member 30 on the distal ends are integrally formed (as a single piece) to achieve the compactness thereof. The fixed engagement members 30, the movable engagement member 31, and the seats 34 and 35 are preferably formed of a heat resistant resin such as PEEK (polyetheretherketone), in terms of improvement in their durability and of preventing them from serving as contaminant sources.